



TecNu, Inc.

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PRESS RELEASE

FOR IMMEDIATE RELEASE

TECNU, INC.

UNVEILS DURAPROCESS™, WAVE SEQUENCING POWER SUPPLY

DuraProcess™ benefits plating of complex geometry's such as PWB's

Highlands Ranch, Colorado USA; April 3, 2000 – TecNu, Inc. officially announced today its DuraProcess™ line of wave sequencing electroprocessing power supplies – at IPC Printed Circuits Expo 2000 (booth 1619).

TecNu™ has produced a patent pending power supply capable of generating a sequence of controlled wave forms for the purpose of electroplating complex or difficult to plate surfaces (such as printed wiring boards) while increasing process automation and capability.

"The USA and international metal finishing industries, continue to be challenged by OEM customer requirements to improve deposit characteristics over more difficult to plate geometry's, lower costs and increased production through put," said Enrique Gutiérrez, president of TecNu. "These challenges require the significant process improvements provided by our DuraProcess™ line of Power Supplies."

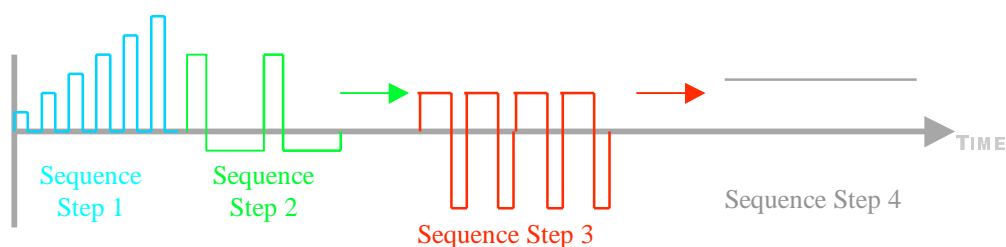
TecNu's™ DuraProcess™ product combines advanced microprocessor technology, switch-mode power conversion electronics and an ergonomic digital user interface. The result is a reliable and user friendly production tool. The operator interface is based on a menu driven control system, which presents only the required information to avoid confusion or overwhelming the operator in a production situation. Additionally, the DuraProcess™ power supply stores wave sequences into a "Job Library", potentially reducing operator error, process time, set up time in production, while increasing production through put.

The DuraProcess™ Wave Sequencing power supply can sequentially deliver any combination of:

- low ripple direct current (DC) output
- ramped DC output
- periodic pulse output
- ramped periodic pulse output
- periodic pulse reverse output
- ramped Periodic pulse reverse output

A typical four step Wave Sequence which may be programmed into a "Job Library Location", is demonstrated below.

Wave Sequence



- SEQUENCE STEP 1** Ramped Periodic Pulse
Purpose: Allows for gradual material build up on the surface in order to avoid burning (applicable to plating on thin films or thin traces)
- SEQUENCE STEP 2** Periodic Pulse Reverse
Purpose: Properly deposits into smaller micro-vias.
- SEQUENCE STEP 3** Periodic Pulse Reverse
Purpose: Properly deposits into larger plated through holes.
- SEQUENCE STEP 4** DC
Purpose: This process step is not required but when applied replaces the matte finish typically associated with pulse wave forms and applies a brighter finish.

TecNu™ a leader in electroprocessing power deliver systems has been first to market and/or the only company to date to provide:

- Microprocessor integrated plating power supply operation
- Menu driven controls
- Environmentally sealed switch-mode mechanical design
- Front panel digital calibration for ISO9000 compliance
- Mod-Bus RS485 digital signal interface
- Gradient wave forms
- Wave sequencing

TecNu™ was founded in 1991 to promote affordable power conversion and microprocessor technology to the Metal Finishing industry.

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